



FOR IMMEDIATE RELEASE

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SHENMAO to Highlight High-Rel Solder Sphere and Thermal Fatigue Resistant Paste at APEX

SAN JOSE, CA — January 2022 — SHENMAO America, Inc. is pleased to announce plans to exhibit in Booth #2534 during the 2022 IPC APEX EXPO, scheduled to take place Jan. 25-27, 2022 at the San Diego Convention Center in California. The company will highlight its PF918-S High Reliability Solder Sphere and PF918-P250 Thermal Fatigue Resistance Lead-free Solder Paste. The new paste is formulated with the new SHENMAO Sn/4Ag/3Bi Alloy design with high thermal impact reliability.

PF918-S Solder Sphere shows more than two times the reliability in both drop test and thermal cycling test compared to SAC405 alloy on automotive electronic devices.

PF918-P250 Solder Paste can increase thermal reliability performance by a minimum of 30 percent. It provides better mechanical shock performance than typical solder alloys such as SAC305 and SAC405, and is suitable for use in consumer electronics, servers and automotive electronics applications.

PF918-P250 has a similar melting point to SAC305 so that the regular SAC305 reflow profile can be applied. With the innovative flux design, voiding can be easily controlled to less than 10 percent.

SHENMAO has successfully been approved by many international well-known electronic manufacturers. The company strives to offer the best quality without compromising cost and time-to-market while providing maximum value to all customers. SHENMAO America, Inc. blends SMT solder paste at its facility in San Jose, CA for distribution in North America.



For more information, please visit www.shenmao.com.

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About SHENMAO

SHENMAO is dedicated to the production of solder products including Water Soluble and No-clean Solder Paste, Laser Solder Paste, Solder Preforms, Cored Solder Wire, Wave Solder Bar Alloys, Wave Soldering Fluxes, Extremely Pure Solder Powder up to Type 8, BGA and Micro BGA Solder Sphere, Wafer Level Packaging Solder Paste and Fluxes, LED Die Attach Paste, High Performance Liquid Fluxes, Solder Preform, Solar Ribbon, Plating Anode used in PCB Fabrication, Assembly and Semiconductor Packaging Processes.